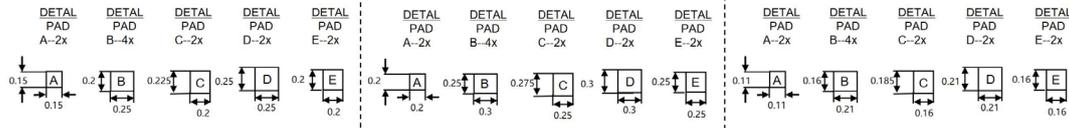
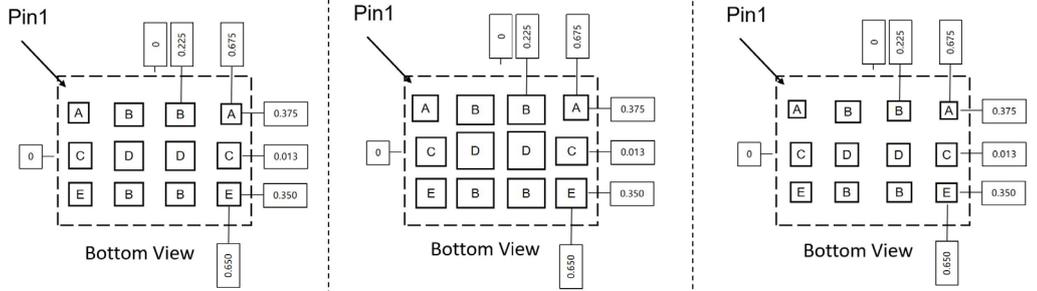
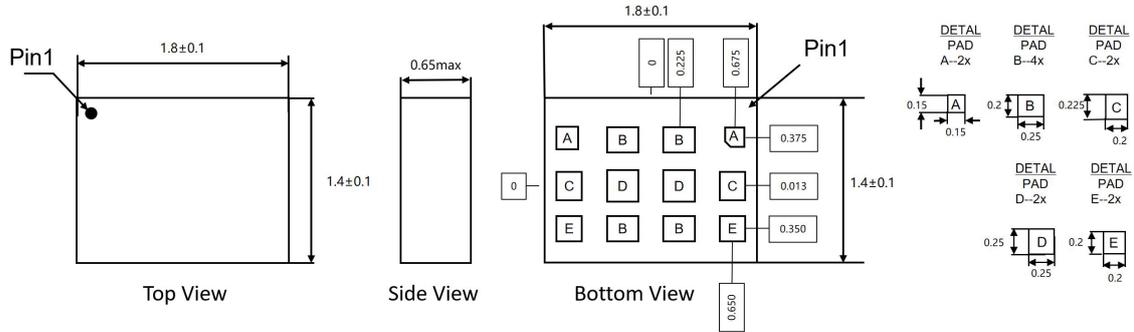


Specification Sheet

Customer Name	XXXX	CUST P/N	NA
Approval No.	PD	Temwell P/N	STSF-5662B345-S1814W
Lot No.		Date	2025.06.13
Description	SAW Filter (BandPass)	Version	A1

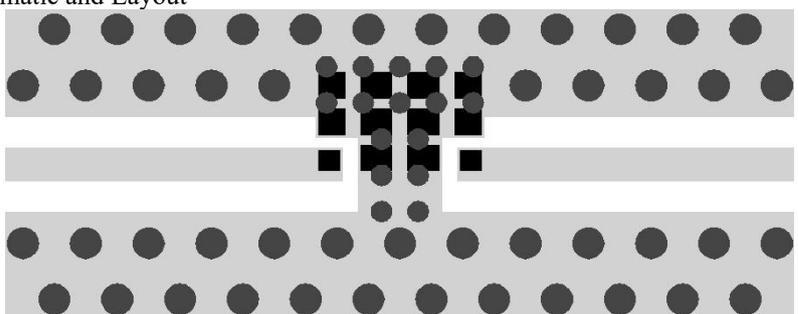
(1) Size Diagram and PCB Mounting Pattern (Unit : MM)

- All tolerances are ± 0.05 mm except overall length and width ± 0.10 mm.

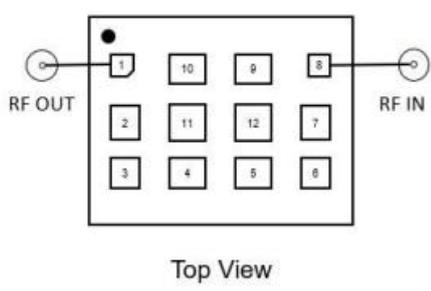


Recommended PCB Metal Top View Recommended Solder Mask Opening Top View Recommended Stencil Pattern Top View

- Evaluation Board Schematic and Layout



(2) Test Circuit



Pin No.	Label	Description
1	OUTPUT	RF Output matched to 50 Ω
8	INPUT	RF Input matched to 50 Ω
Other Pads	GND	RF/DC ground. Use the recommended via pattern to minimize inductance and thermal resistance. Refer to PCB Mounting Pattern for suggested footprint.

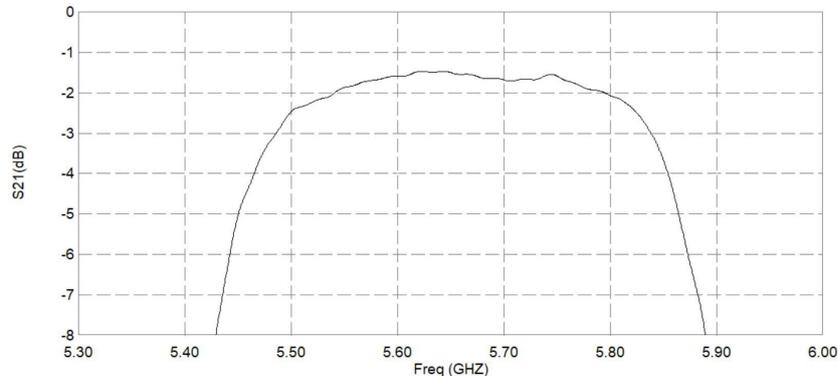
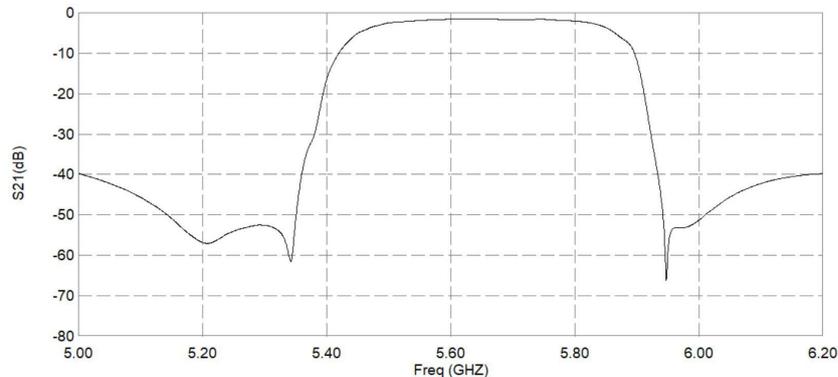
(3)Electrical Specifications

Item		Specification			
Parameter	MHz	Unit	Min.	Typical	Max.
Center Frequency	-	MHz	-	5662	-
Insertion Loss	5490-5835 (345MHz)	dB	-	1.9	2.3
	5490-5835 (Any 160MHz)	dB	-	1.9	2.4
	5490-5835	dB	-	2.9	3.3
Inband Ripple	5490-5835	dB	-	1.4	1.6
VSWR of Input Port	5490-5835	-	-	1.6	1.8
VSWR of Output Port	5490-5835	-	-	1.6	1.8
Attenuation	30-2400	dB	24	26	-
	2400-2500	dB	24	26	-
	2400-3000	dB	20	22	-
	3400-3800	dB	25	27	-
	3800-4900	dB	26	28	-
	4400-4800	dB	28	30	-
	4800-5000	dB	32	35	-
	5170-5330	dB	50	52	-
	7200-7500	dB	37	39	-
10300-11800	dB	21	23	-	
Operation Temperature	-40°C~+105°C	°C	-	-	-
Storage Temperature	-40°C~+105°C	°C	-	-	-
RF Power Dissipation	+28	dBm	-	-	-
DC Voltage	3	V	-	-	-

Remark

Note 1: Test Temperature: 25°C±2°C

Note 2: Terminating source impedance: 50Ω. Terminating load impedance: 50Ω

Figure 1 Electrical Characteristics:Passband

Figure 2 Electrical Characteristics: Narrowband

Figure 3 Electrical Characteristics: Wideband

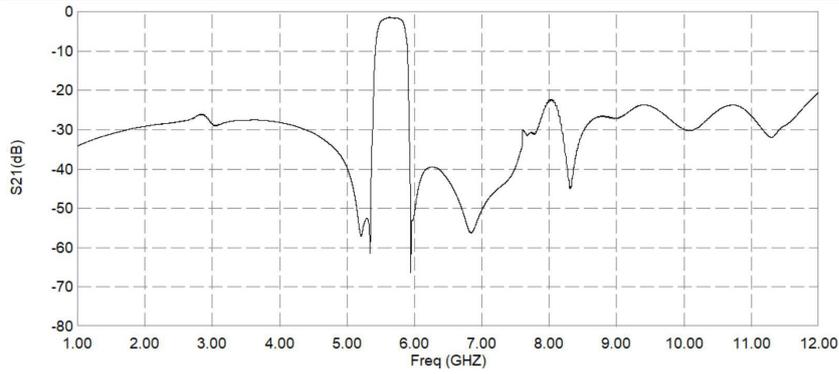


Figure 4 Electrical Characteristics: Input port Return Loss

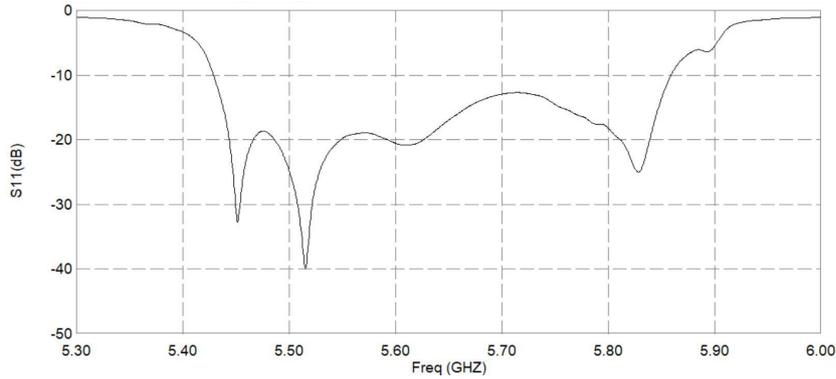


Figure 5 Electrical Characteristics: Output port Return Loss

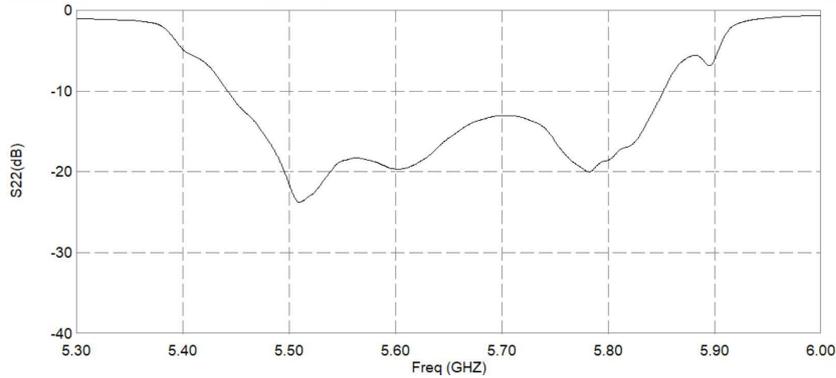
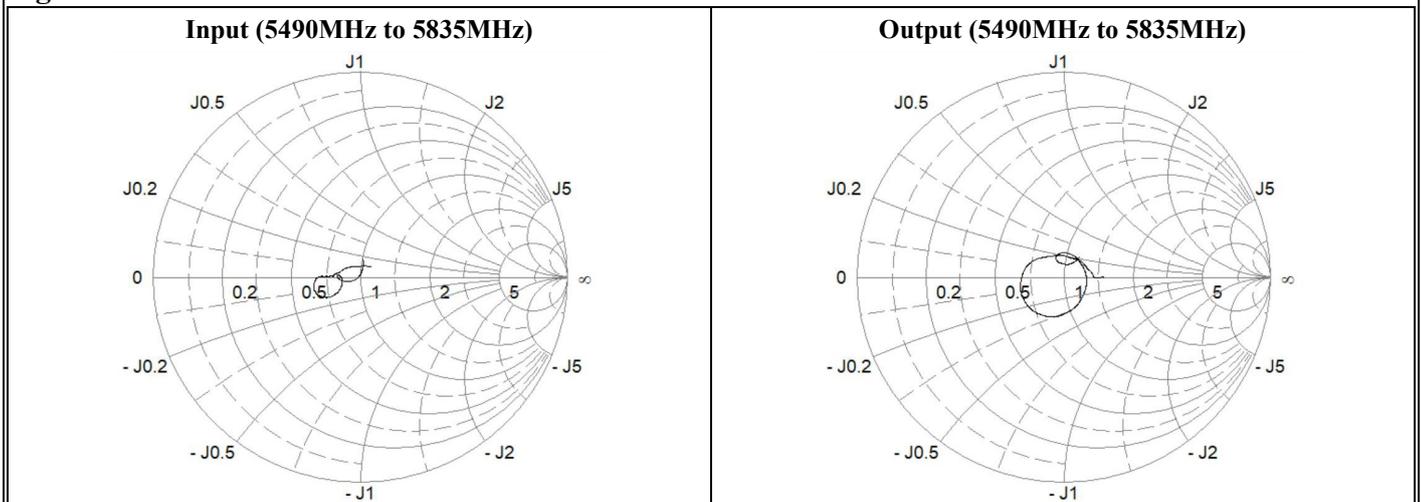
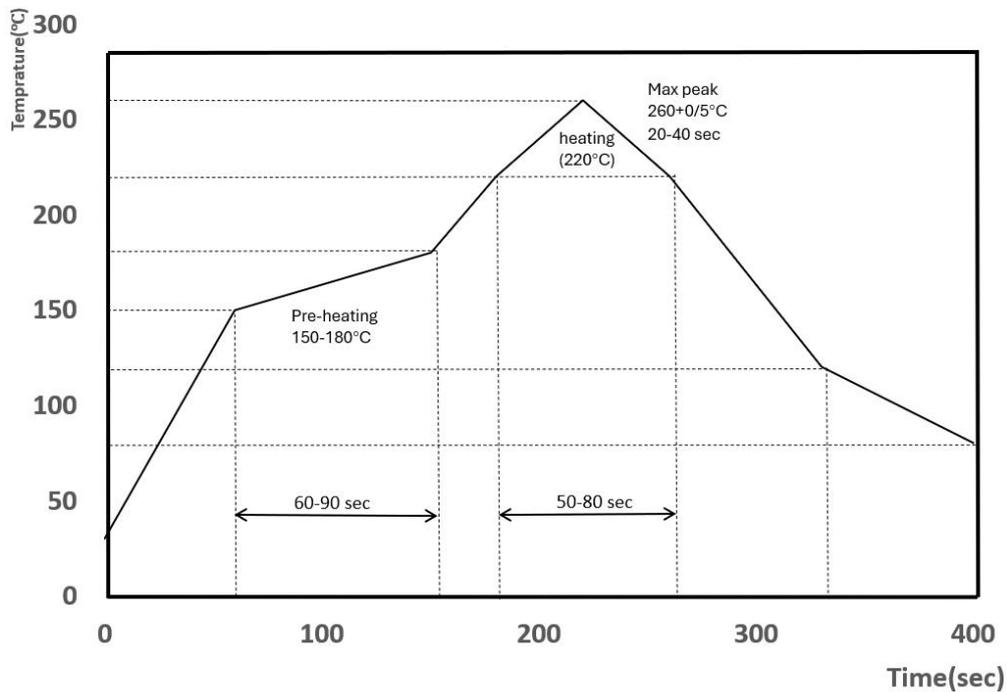


Figure 6 Smith Chart



Approval	Supervisor	Designer
C. K. Chang	M. Y. Chen	F.L.Lai

Recommended SMT Solder Profile



Reliability

No.	Test item	Test condition	
1	Temperature Storage	Temperature: 105°C±2°C , Duration: 250h , Recovery time: 2h±0.5h Temperature: -40°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h	
2	Humidity Test	Conditions: 60°C±2°C ,90~95%RH	Duration:250h
3	Thermal Shock	Heat cycle conditions: TA=-40°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.	
4	Vibration Fatigue	Frequency of vibration:10~55Hz Directions: X,Y and Z	Amplitude:1.5mm Duration: 2h
5	Drop Test	Cycle time:10times	Height:1.0m
6	Solder Ability Test	Temperature:245°C±5°C Depth: DIP--2/3, SMD--1/5	Duration:3.0s--5.0s
7	Resistance to Soldering Heat	Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration:10±1s Temperature of Soldering Iron: 350°C±10°C, Duration: 3~4s, Recovery time : 2 ± 0.5h	